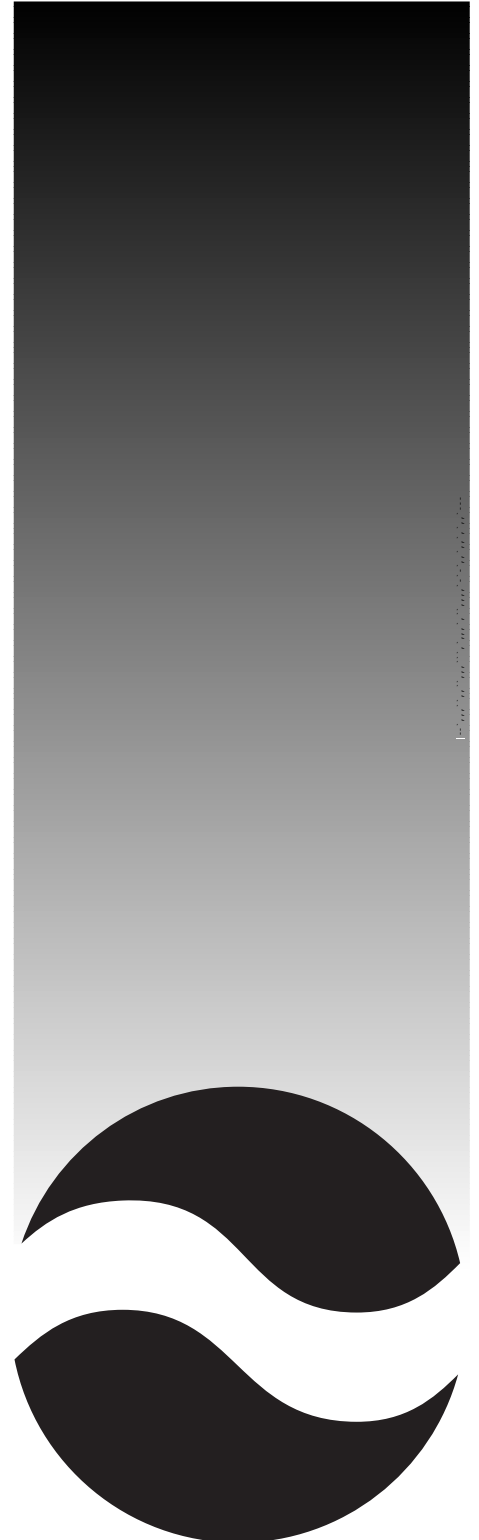


J-STD-027
FEBRUARY 2003

JOINT INDUSTRY STANDARD

Mechanical
Outline Standard
for Flip Chip
and Chip Size
Configurations



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J-STD-027

Mechanical Outline Standard for Flip Chip and Chip Size Configurations

About This Document

This document is intended to report on the work being done by several organizations concerned with the design of bare die in flip chip or chip scale configurations. Details were developed by companies who have implemented the processes described herein and have agreed to share their experiences. Readers are encouraged to communicate to the appropriate trade associations or societies any comments or observations regarding details published in this document, or ideas for additional details that would serve the industry.

Users of this standard are encouraged to participate in the development of future revisions.

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Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the Flip Chip Task Group (5-21g) of the Assembly and Joining Processes Committee (5-20) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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